



## PRODUCT DATA SHEET

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**Datasheet**



**Resources**



**Samples**

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at [www.jg-semi.cn](http://www.jg-semi.cn). Please email any questions regarding the system integration to [JINGAO\\_questions@jgsemi.com](mailto:JINGAO_questions@jgsemi.com).

## Features

- Low forward voltage
- Thin & leadless package for space saving
- Pb free version, RoHS compliant,  
and Halogen free



## Mechanical Characteristics

- Case: DFN1006(0402) mold package
- Terminal: Sn/Au plated, solderable per  
MIL-STD-750, method 2026
- Marking: cathode band & BP
- Weight: 0.001 gram(approx.)

## DFN1006(0402)



## Maximum Rating And Electrical Characteristics (at Ta=25°C unless otherwise noted)

Parameter	Condition	Symbol	Min	Typ	Max	Unit
Repetitive peak reverse voltage		VRRM			40	V
Reverse voltage		VR			40	V
Average forward current		Io			100	mA
Forward current surge peak	8.3 ms single half sine-wave superimposed on rate load ( JEDEC method)	IFSM			1	A
Storage/Operation temperature		T <sub>sgt</sub>	-40		125	°C
Junction temperature		T <sub>j</sub>			125	°C
Forward voltage	IF1=10mA IF2=20mA IF3=100mA	VF			0.29 0.30 0.40	V
Reverse current	VR=30V	IR			30	uA

## Typical Characteristics

Fig.1-forward characteristics

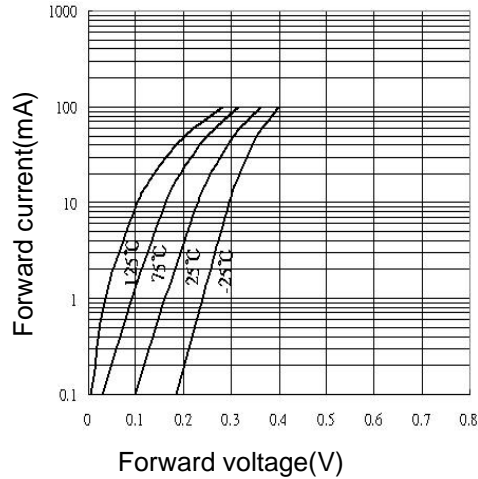


Fig.2-Reverse characteristics

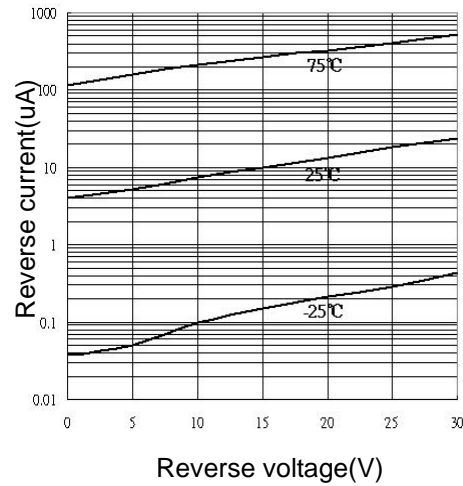


Fig.3 - Capacitance between terminals characteristics

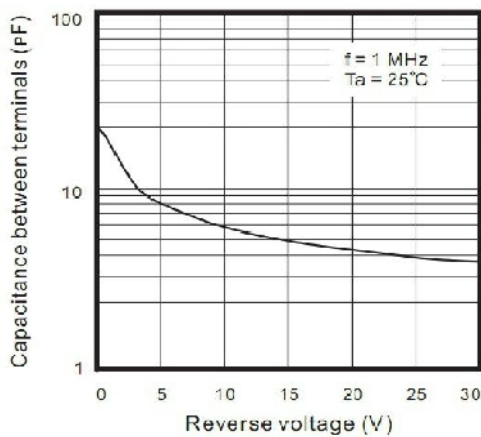


Fig.4 - Current derating curve

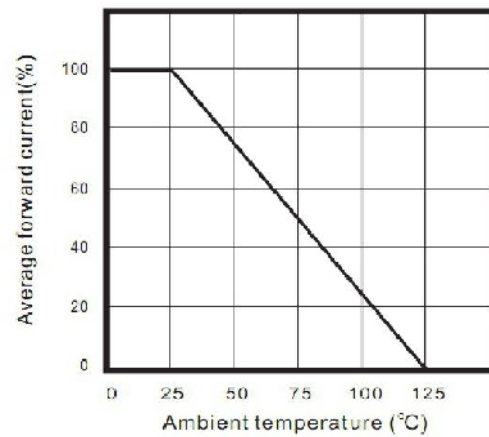


Fig. 5 - VF Dispersion map

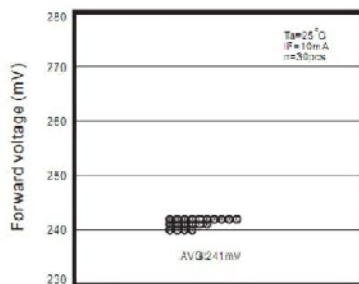


Fig. 6 - IR Dispersion map

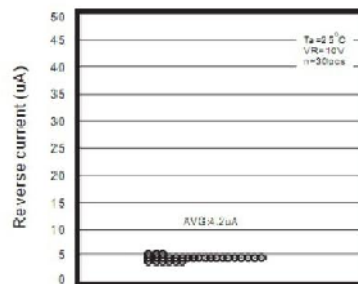
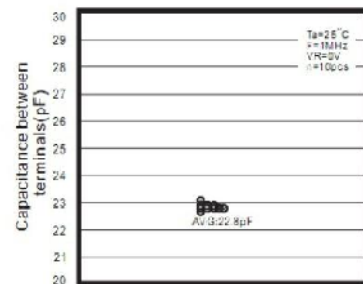
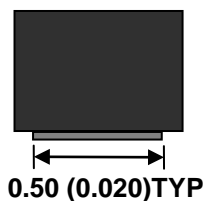
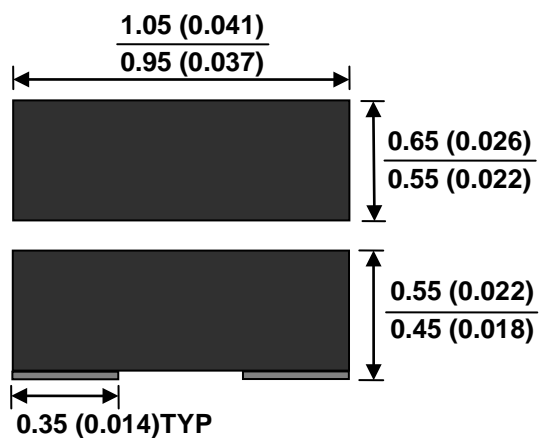


Fig. 7 - CT Dispersion map



**Packing Specification**
**DFN1006(0402)**


Dimensions in millimeter and (inches)

**Tape & Reel Dimensions**

Package	Unit	A	B	C	d	D
DFN1006	mm	0.67±0.10	1.12±0.10	0.60±0.10	1.50±0.10	178±1
	inch	0.026±0.004	0.044±0.004	0.024±0.004	0.060±0.004	7.008±0.04

Package	Unit	D1	D2	E	F	P
DFN1006	mm	60MIN	13.0±0.20	1.75±0.10	3.5±0.10	4.0±0.10
	inch	2.362MIN	0.512±0.008	0.069±0.004	0.138±0.004	0.157±0.004

Package	Unit	P0	P1	T	W	W1
DFN1006	mm	4.0±0.10	2.0±0.10	0.22±0.03	8.0±0.10	13.5MAX
	inch	0.157±0.004	0.079±0.004	0.009±0.002	0.315±0.004	0.531MAX

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